

Amendment to the Title:

Please replace the title with the following amended title:

~~METHOD OF PRESSURE CURING FOR REDUCING VOIDS IN A DIE ATTACH BONDLINE AND APPLICATION THEREOF~~
PRESSURE AND HEAT CURED SEMICONDUCTOR DIE PACKAGES HAVING REDUCED VOIDS IN A DIE ATTACH BONDLINE

In the Specification:

Amend the specification by inserting a new section before the "Technical Field" as follows:

-- CROSS-REFERENCE TO RELATED APPLICATION

This application is a continuation of pending United States Patent Application No. 09/895,662, filed June 29, 2001, which is a divisional of U.S. Pat. Application No. 09/515,579, filed February 29, 2000, now U.S. Pat. No. 6,524,891. --